

STGWT40HP65FB-VB Datasheet

650V Trench and Fieldstop IGBT

| PRODUCT SUMMARY | | |
|-------------------|----------------|----------------|
| V_{CE} (V) | 650 | |
| I_C (A) | 120 (TC=25 °C) | 60 (TC=100 °C) |
| $V_{CE(sat)}$ (V) | 1.7 | |
| I_{CM} (A) | 180 | |

FEATURES

- Very Low V_{CEsat}
- Low turn-off losses
- High speed switching
- Maximum junction temperature 175°C
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)



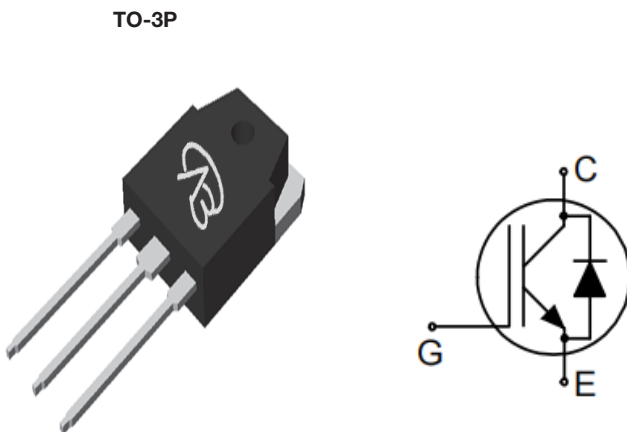
RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Consumer and computing
 - ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- Renewable energy
 - Solar (PV inverters)
- Switch mode power supplies (SMPS)

Package pin definition

- Pin1 G - Gate
- Pin2 C & backside - Collector
- Pin3 E - Emitter



Top View

| ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ °C}$, unless otherwise noted) | | | |
|---|------------------------------|-----------------------|-------------|
| PARAMETER | SYMBOL | LIMIT | UNIT |
| Collector-Emitter Voltage | V_{CE} | 650 | V |
| Gate-Emitter Voltage | V_{GE} | ± 30 | |
| Continuous Collector Current ($T_J = 150\text{ °C}$) | V_{GE} at 15 V | $T_C = 25\text{ °C}$ | 120 |
| | | $T_C = 100\text{ °C}$ | 60 |
| Pulsed Collector Current ^a | | I_{CM} | 180 |
| Diode Forward Current ^b | | I_F | 60 |
| Maximum Power Dissipation | | $T_C = 25\text{ °C}$ | 450 |
| | | $T_C = 100\text{ °C}$ | 200 |
| Operating Junction and Storage Temperature Range | | T_J, T_{stg} | -55 to +175 |
| Short Circuit Withstand Time $T_C=150$ | $V_{GE}= 15V, V_{CE} = 400V$ | tsc | 3 |
| Short Circuit Withstand Time $T_C=100$ | | | 5 |
| Soldering Recommendations (Peak Temperature) ^c | for 10 s | | 260 |

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- Current limited by maximum junction temperature.
- 1.6 mm from case.

| THERMAL RESISTANCE RATINGS | | | | |
|-----------------------------|------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | R_{thJA} | - | 40 | °C/W |
| Maximum Junction-to-Case | R_{thJC} | - | 0.5 | |

| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | |
|---|---------------|--|------------|--------|--------|---------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | |
| Collector-Emitter Breakdown Voltage | BV_{CE} | $V_{GE} = 0\text{ V}, I_C = 250\text{ }\mu\text{A}$ $V_{GE} = 0\text{ V}, I_C = 1\text{ mA}$ | 650 650 | - - | - - | V |
| Gate-Source Threshold Voltage (N) | $V_{GE(th)}$ | $V_{CE} = V_{GE}, I_D = 250\text{ }\mu\text{A}$ | 4 | 5 | 6 | V |
| Zero Gate Voltage Collector Current | I_{CES} | $V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}, T_J = 25\text{ }^\circ\text{C}$ | - | 1 | 20 | μA |
| | | $V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$ | - | 1000 | - | μA |
| Gate-Emitter Leakage Current | I_{GES} | $V_{CE} = 0\text{ V}, V_{GS} = \pm 2.0\text{ V}$ | - | - | 100 | nA |
| Collector-Emitter Saturation Voltage | $V_{CE(sat)}$ | $V_{GE} = 15\text{ V}$ $I_C = 60\text{ A}$ | - | 1.8 | 2.1 | V |
| Forward Transconductance | g_{fs} | $V_{CE} = 20\text{ V}, I_C = 60\text{ A}$ | - | 40 | - | S |
| Dynamic | | | | | | |
| Input Capacitance | C_{ies} | $V_{GE} = 0\text{ V}, V_{CE} = 25\text{ V},$ $f = 500\text{ KHz}$ | - | 6210 | - | pF |
| Output Capacitance | C_{oes} | | - | 228 | - | |
| Reverse Transfer Capacitance | C_{res} | | - | 60 | - | |
| Turn-on Energy | E_{on} | $V_{CE} = 400\text{ V}, V_{GE} = 0/15\text{V},$ $I_C = 60\text{ A}, R_g = 10\Omega$ | - | 0.76 | - | nJ |
| Turn-off Energy | E_{off} | | - | 0.26 | - | |
| Total Gate Charge | Q_g | $V_{GE} = 15\text{ V}$ $I_C = 60\text{ A}, V_{CE} = 400\text{ V}$ | - | 165 | - | nC |
| Gate-Emitter Charge | Q_{ge} | | - | 18 | - | |
| Gate to Collector Charge | Q_{gc} | | - | 2.3 | - | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{CE} = 400\text{ V}, V_{GE} = 0/15\text{V},$ $I_C = 60\text{ A}, R_g = 10\Omega$ | - | 72 | - | ns |
| Rise Time | t_r | | - | 42 | - | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 170 | - | |
| Fall Time | t_f | | - | 26 | - | |
| Internal emitter inductance measured 5 mm | L_E | | - | 13 | - | |
| Diode Characteristics | | | | | | |
| Diode Forward Current | I_F | IGBT symbol showing the integral reverse junction diode | - | - | 60 | A |
| Pulsed Diode Forward Current | I_{FM} | | - | - | 180 | |
| Diode Forward Voltage | V_F | $I_F = 60\text{ A}$ | - | 1.50 | 2.0 | V |
| Reverse Recovery Time | t_{rr} | $T_J = 25\text{ }^\circ\text{C}, I_F = 60\text{ A},$ $di/dt = 200\text{ A}/\mu\text{s}, V_R = 400\text{ V}$ | - | 60 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | - | 0.3 | - | μC |
| Reverse Recovery Current | I_{RRM} | | - | 11 | - | A |

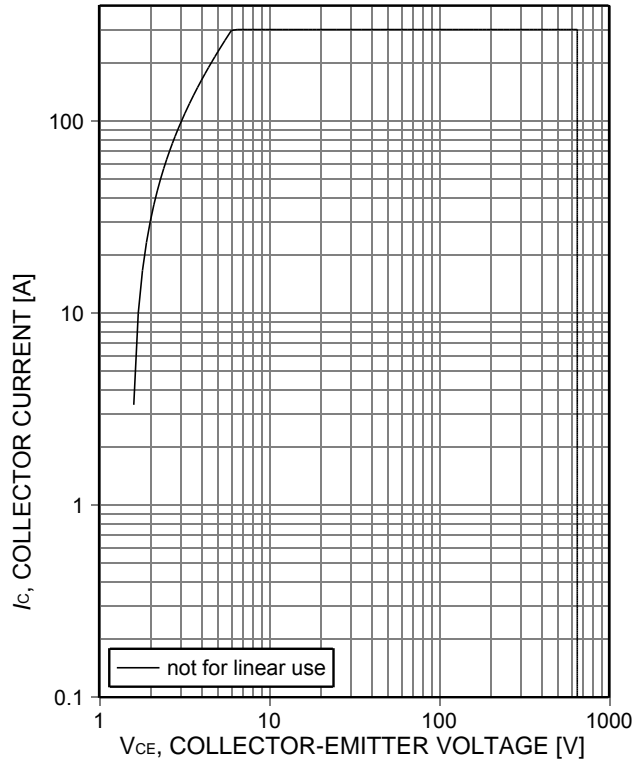


Figure 1. Forward bias safe operating area



Figure 2. Power dissipation as a function of case

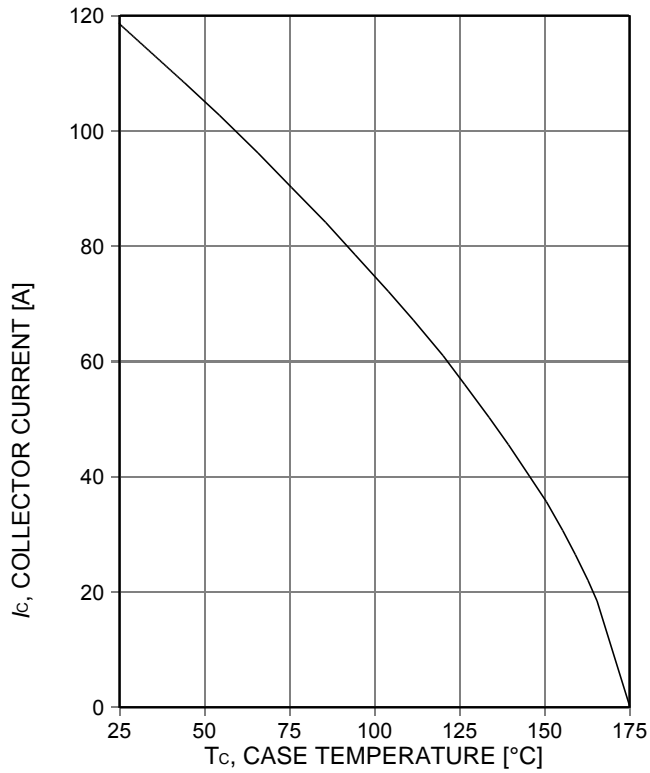


Figure 3. Collector current as a function of case temperature



Figure 4. Typical output characteristic

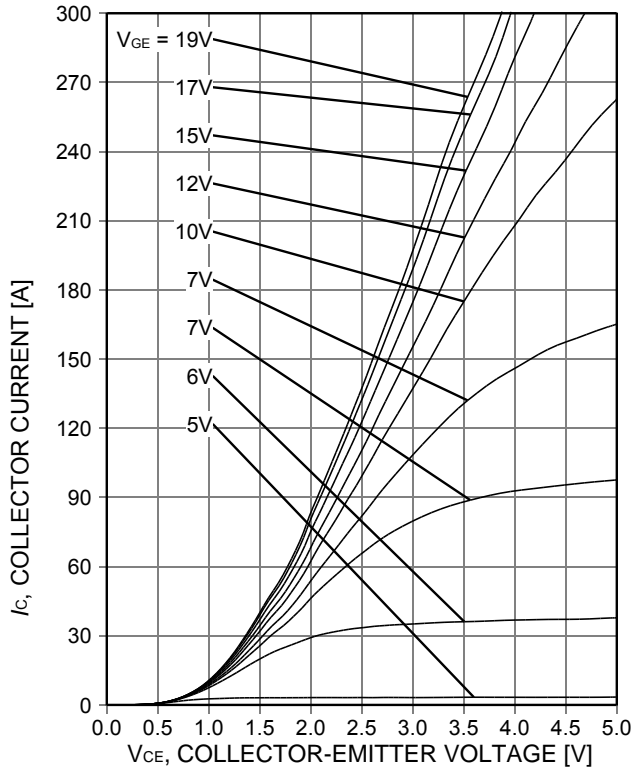


Figure 5. Typical output characteristic



Figure 6. Typical transfer characteristic

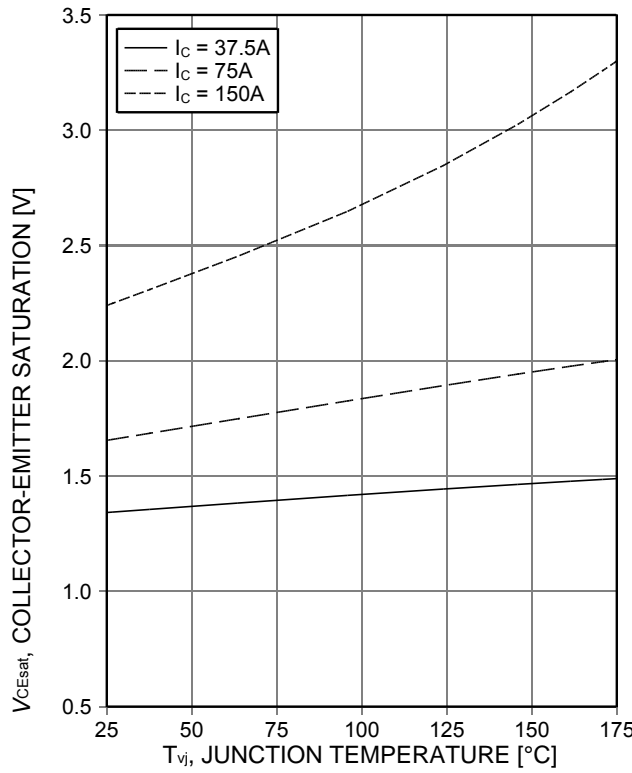


Figure 7. Typical collector-emitter saturation voltage as a function of junction temperature

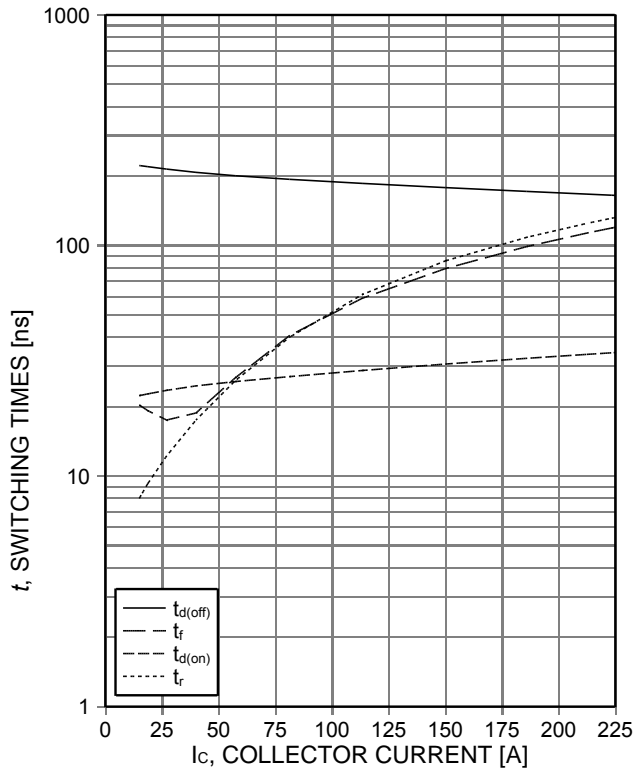


Figure 8. Typical switching times as a function of collector current

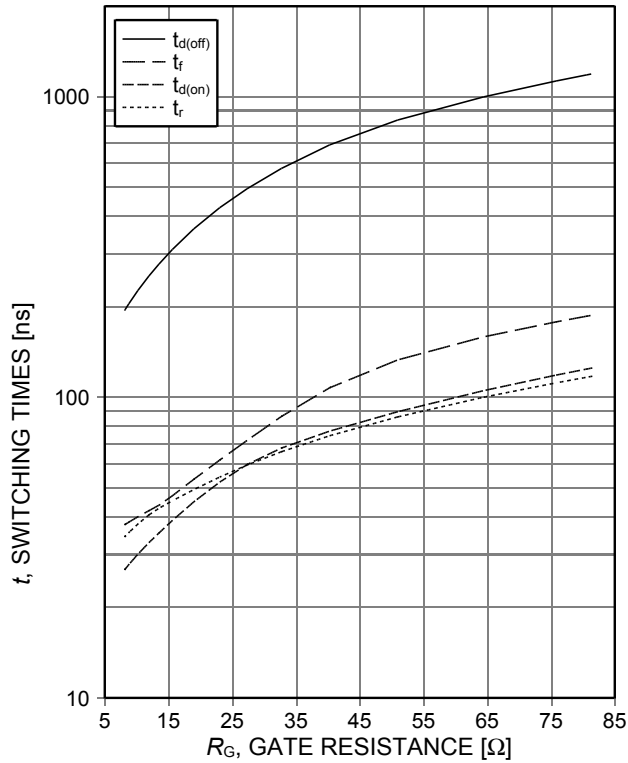


Figure 9. Typical switching times as a function of gate resistance

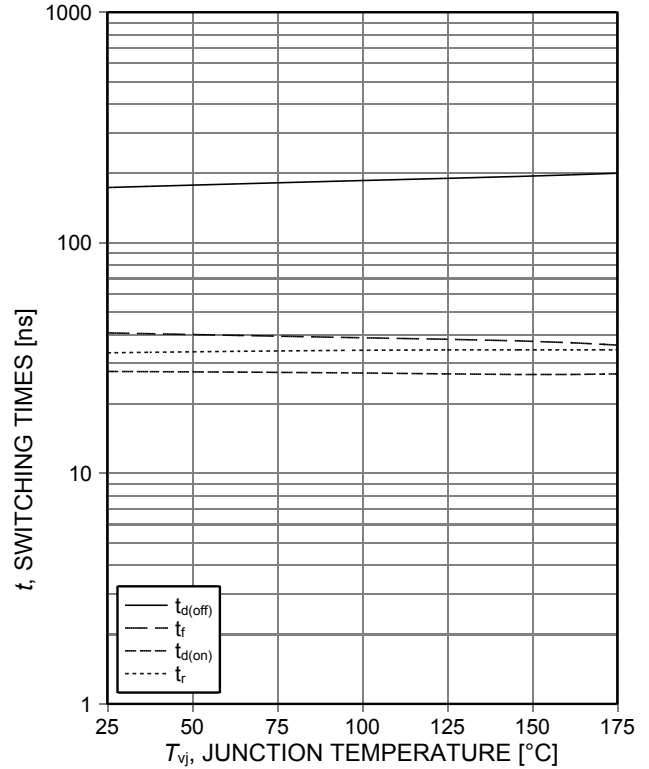


Figure 10. Typical switching times as a function of junction temperature

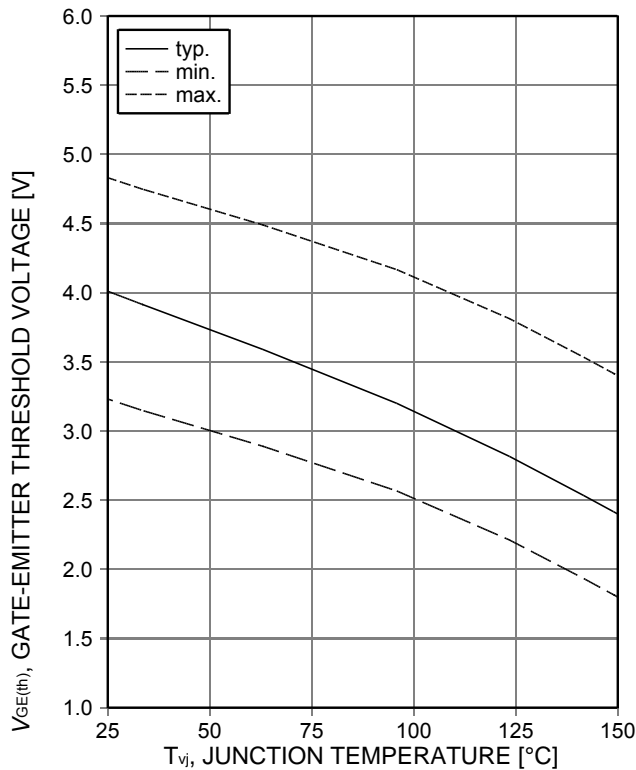


Figure 11. Gate-emitter threshold voltage as a function of junction temperature

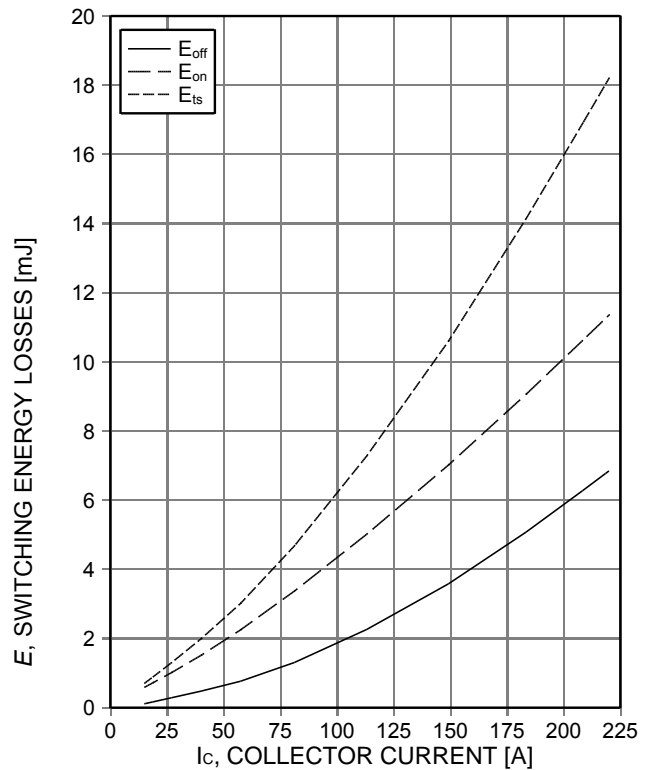


Figure 12. Typical switching energy losses as a function of collector current

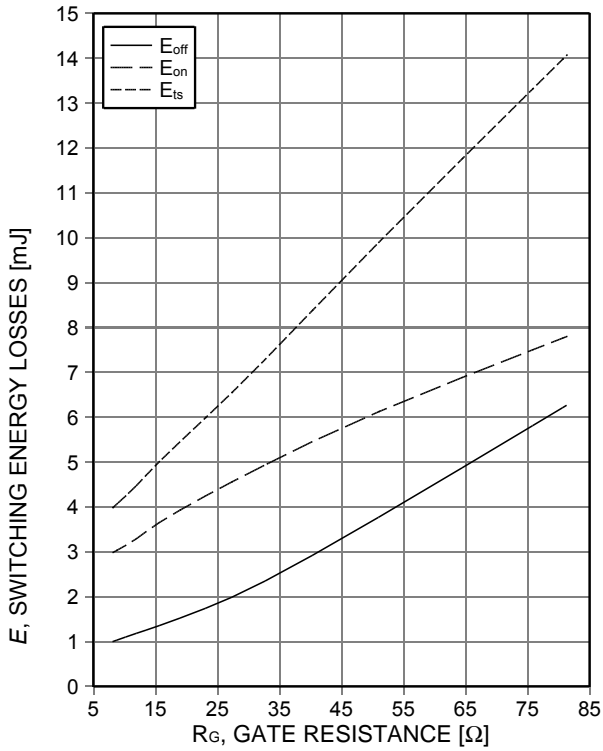


Figure 13. Typical switching energy losses as a function of gate resistance

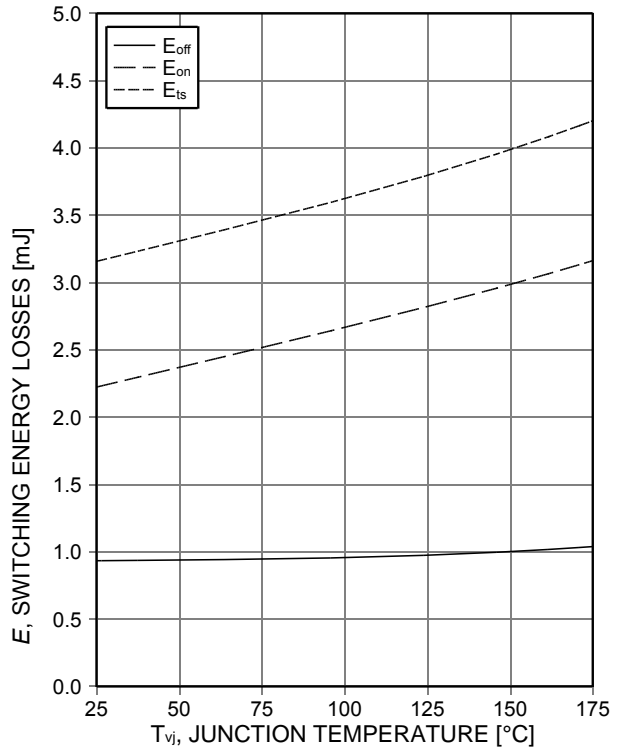


Figure 14. Typical switching energy losses as a function of junction temperature

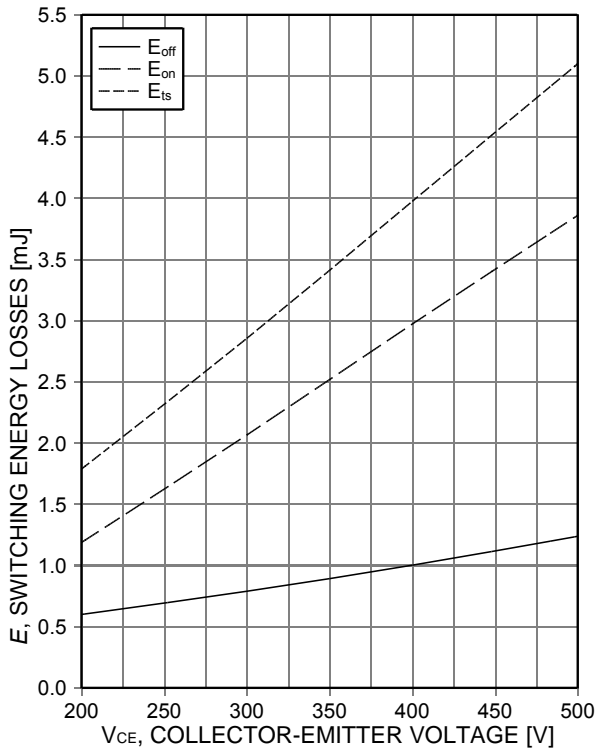


Figure 15. Typical switching energy losses as a function of collector emitter voltage

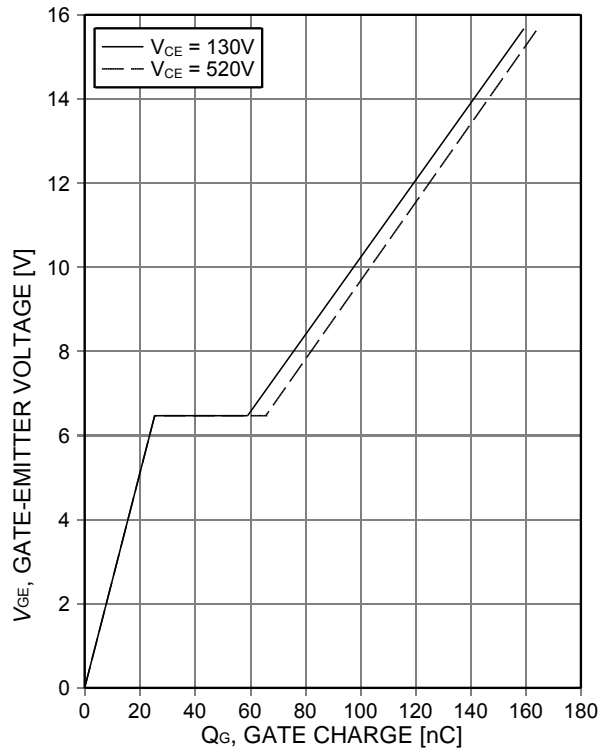


Figure 16. Typical gate charge



Figure 17. Typical capacitance as a function of collector-emitter voltage

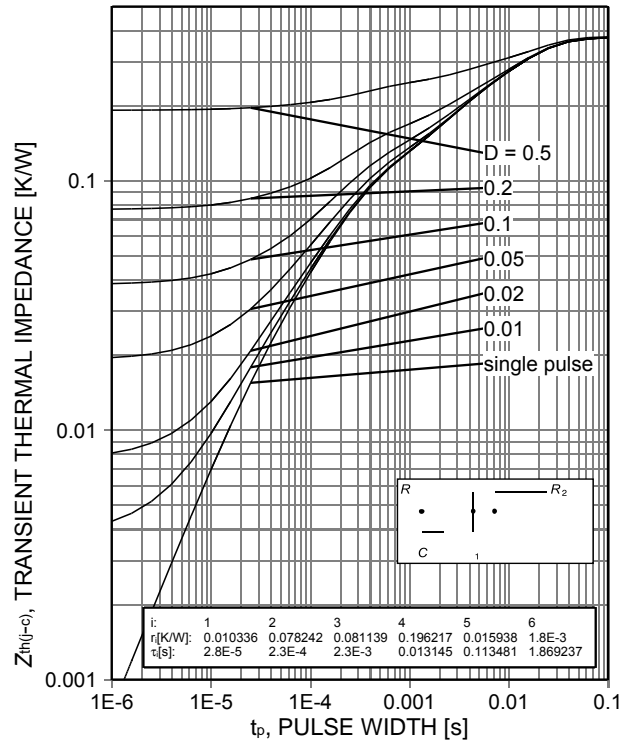
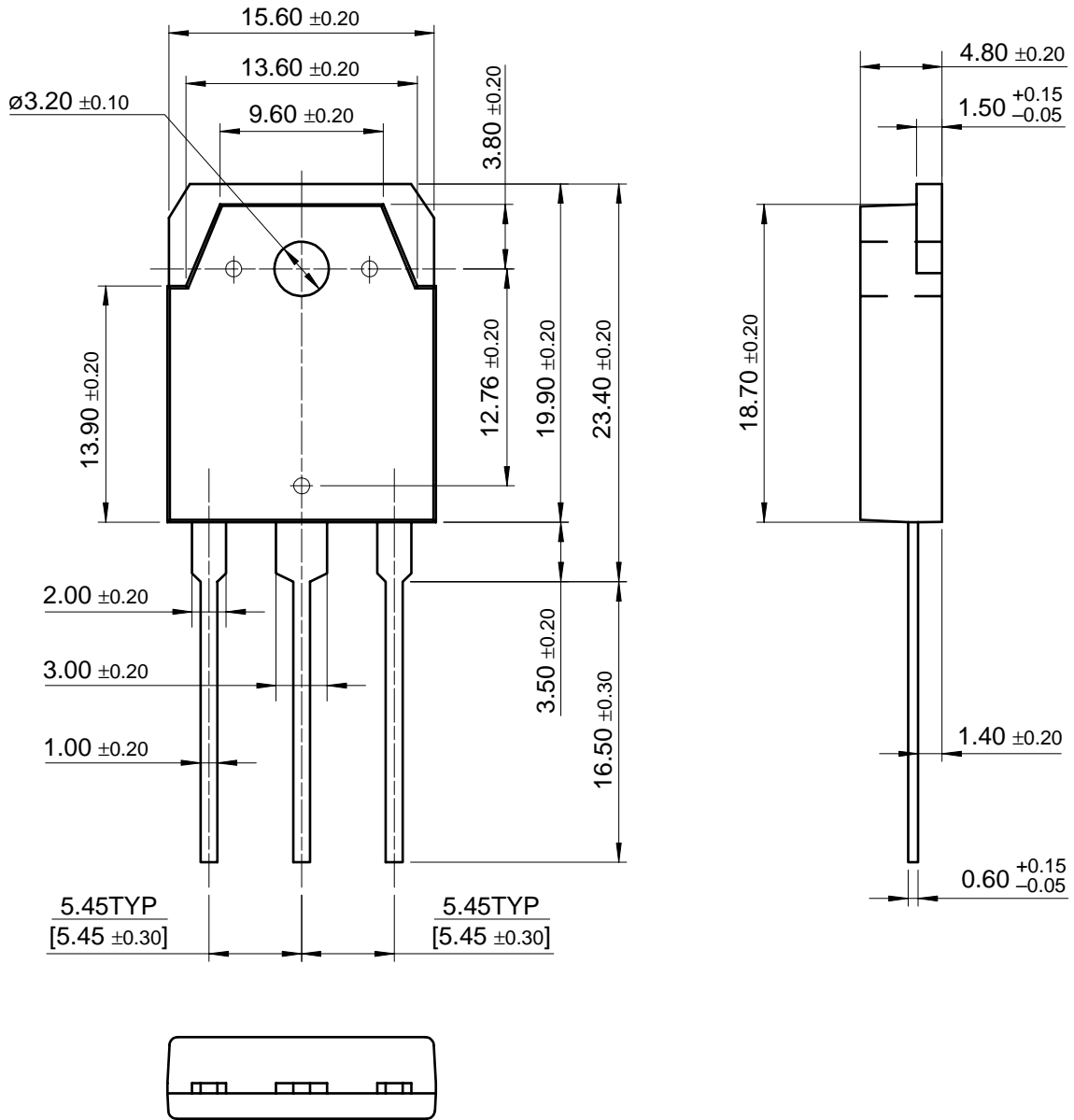


Figure 18. IGBT transient thermal impedance

TO-3P



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